

PACKAGE ASSEMBLY

ABSTRACT OF THE DISCLOSURE

A package assembly includes a housing frame, a power module, a first heat dissipating module and a second heat dissipating module. The housing frame is fixed on the first heat dissipating module. The power module is disposed within a hollow part of the housing frame, and covers a first open end of the hollow part. The power module includes a first surface, a second surface and at least one pin. The first surface has a periphery region and a middle region. The second surface is attached on the first heat dissipating module. The at least one pin is disposed on the periphery region. The at least one pin is penetrated through the corresponding opening and partially exposed outside the housing frame. The second heat dissipating module is disposed within the hollow part and attached on the middle region of the first surface of the power module.

[FIG. 1]